

客户图

NOTES:

.FINISH:

1.1 HOUSING: LCP,UL94V-0.

1.2 CONTACT: PHOSPHOR BRONZE SELECTIVE GOLD
(SEE ORDER INFORMATION) PLATED IN CONTACT
AREA.40u"MIN TIN PLATED IN SIDER AREA.
30u"MIN.NICKEL UNDERPLATED OVERLL.

1.3 NAIL:COPPER ALLOY,40U"MIN TIN PLATED ON SURFACE.
30U"MIN.NICKEL UNDERPLATED OVERALL.

1.4 VACUUM COVER:STAINLESS STEEL

2. ELECTRICAL:

2.1 CURRENT RATING: 0.5A FOR VBUS PIN;

2.2 DIELECTRIC WITHSTANDING VOLTAGE: 250V AC/MINUTE.

2.3 CONTACT RESISTANCE: 50mΩ MAX.

2.4 INSULATION RESISTANCE: 1000mΩ MIN

3.OPERATING TEMPERATURE:-40°C~+105°C

4.Max Processing Temp:265°C Seconds 10S

5.ORDER INFORMATION:

66B3-M XXX XX XXX R 01

Pin数码

SEE TABLE

030=2x15PIN

050=2x25PIN

.....

端子电镀:

G0=Gold Flash(全金)

G1=1u" Gold

G2=3u" Gold

G3=5u" Gold

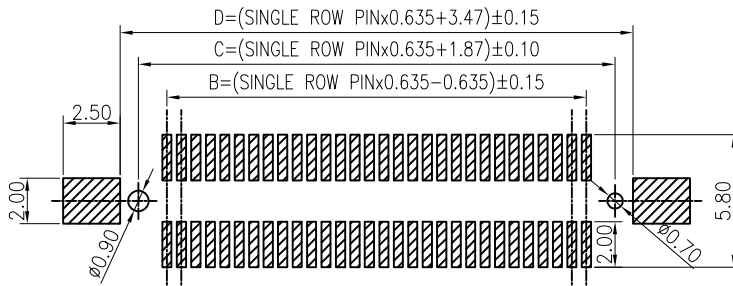
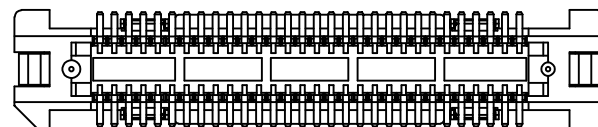
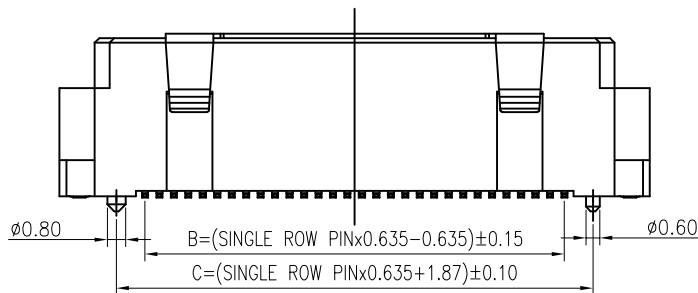
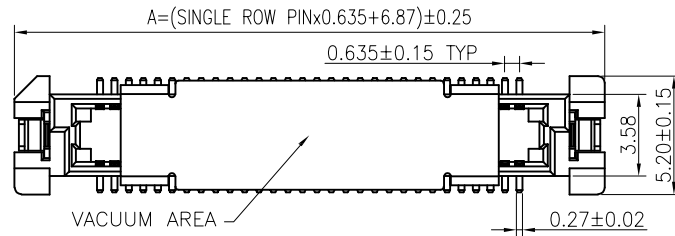
塑胶高度(H1):

070=7.00mm

090=9.00mm

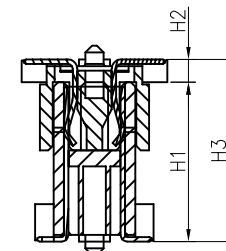
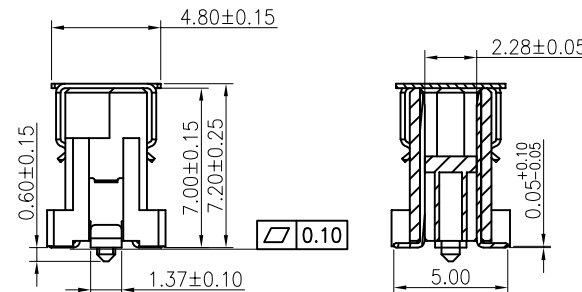
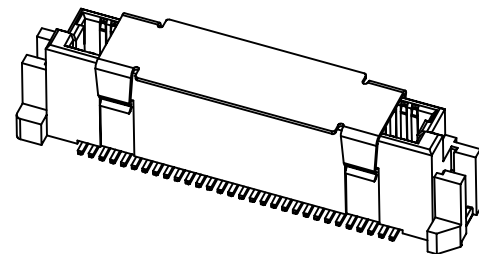
包装方式:

R=TAPE REEL



RECOMMENDED PCB LAYOUT(PCB THICKNESS:1.6mm)

COMPONENT SIDE VIEW(TOLERANCE:±0.05)



MATING HEIGHT

MATING HEIGHT	H1	H2	H3
8.00mm	7.00	1.00	8.00
10.00mm	9.00		10.00

No.OF PIN	Dimensions			
	A	B	C	D
040=2*20PIN	19.57	12.065	14.57	16.17
060=2*30PIN	25.92	18.415	20.92	22.52
080=2*40PIN	32.27	24.765	27.27	28.87
100=2*50PIN	38.62	31.115	33.62	35.22
120=2*60PIN	44.97	37.465	39.97	41.57
140=2*70PIN	51.32	43.815	46.32	47.92
160=2*80PIN	57.67	50.165	52.67	54.27
180=2*90PIN	64.02	56.515	59.02	60.62
200=2*100PIN	70.37	62.865	65.37	66.97

OPERATION

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

DRAW

DESIGN

CHECK

APPROVE

UNIT

Mr.Zeng

Jensen

Jack

Andy

mm

2024.08.07

2024.08.07

2024.08.07

2024.08.07

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 66B3-M XXX XX XXX R 01

SHEET 1/1 TITLE: 66B3_0.635mm BTB 公座板对板

PROJ. DRAW NO. SP-1244

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		